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## GLOSSARY

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*This glossary contains certain technical terms used in this document in connection with us and our business. Such terms and their meaning may not correspond to standard industry definitions or usage.*

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|--------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| “2.5D packaging”         | a semiconductor packaging technology where chips are placed side by side on a silicon interposer, enabling high-bandwidth interconnection between them                                                                   |
| “3C” or “3C electronics” | a collective term for the three major categories (computers, communications and consumer electronics) of electronic products widely used in daily life and industry                                                      |
| “3D packaging”           | a semiconductor packaging technology that stacks multiple chips vertically to enable higher integration density and shorter signal paths compared to conventional planar packaging                                       |
| “ADB”                    | adaptive driving beam, an advanced automotive headlight technology that automatically adjusts the light beam pattern in real time to optimize road illumination while avoiding glare to oncoming traffic                 |
| “AEC”                    | active electrical cable, a type of high-speed copper cable with integrated active components that amplify electrical signals, enabling direct signal transmission for data center internal interconnection               |
| “AEC-Q200”               | Automotive Electronics Council Q200, an industry standard for stress test qualification of passive electronic components (such as resistors, capacitors and inductors) used in automotive applications                   |
| “ASIC”                   | application-specific integrated circuit, a microchip custom-designed and manufactured for a particular application or function, offering optimized performance compared to general-purpose processors                    |
| “CAD”                    | computer-aided design, software used to create precision two-dimensional or three-dimensional models of physical objects for engineering, architecture and manufacturing applications                                    |
| “CAM”                    | computer-aided manufacturing, software that uses computer systems to plan, manage and control manufacturing operations, often working in conjunction with CAD to translate designs into production instructions          |
| “CNC”                    | computer numerical control, a manufacturing process that uses pre-programmed computer software to control the movement of machinery and cutting tools, enabling high-precision and automated production of complex parts |

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| “CPO”   | co-packaged optics, an advanced packaging technology that integrates optical engines directly with network switch ASICs on the same package substrate to improve energy efficiency and bandwidth density in data centers                                                                                                                 |
| “DSP”   | digital signal processor, a specialized microprocessor chip with its architecture optimized for the operational needs of digital signal processing, performing rapid mathematical calculations on streaming data                                                                                                                         |
| “DWDM”  | dense wavelength division multiplexing, an optical networking technology that multiplexes a large number of optical carrier signals onto a single optical fiber using closely spaced wavelengths of laser light, significantly increasing transmission capacity                                                                          |
| “ELS”   | external light source, an optical component that generates laser light externally and delivers it via fiber connections to photonic integrated circuits or optical engines, separating the light generation from the data modulation function                                                                                            |
| “EMC”   | electromagnetic compatibility, the ability of an electronic device or system to function as intended in its electromagnetic environment without causing or suffering from electromagnetic interference                                                                                                                                   |
| “EML”   | electro-absorption modulated laser, an integrated optoelectronic semiconductor component that combines a continuous-wave laser diode (typically a DFB laser) and an electro-absorption modulator (EAM) on a single chip, utilized primarily for generating high-speed, low-chirp optical signals in long-haul fiber optic communications |
| “eVTOL” | electric vertical take-off and landing (aircraft), a type of aircraft that uses electric power to hover, take off and land vertically, designed primarily for urban air mobility and short-distance passenger transport                                                                                                                  |
| “F5G”   | the fifth generation fixed network, a next-generation fixed broadband network standard defined by ETSI that delivers ultra-high bandwidth, full-fiber connectivity and enhanced quality of service for enterprise and residential users                                                                                                  |
| “F5G-A” | the fifth generation fixed network-Advanced, an evolved version of F5G technology offering enhanced fixed network capabilities with higher bandwidth, lower latency and improved network intelligence                                                                                                                                    |
| “FPC”   | flexible printed circuit, a type of electronic circuit built on a thin, flexible polymer substrate that can be bent, folded or twisted to fit into compact and irregularly shaped electronic devices                                                                                                                                     |

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| “FPGA”   | field-programmable gate array, a highly flexible semiconductor device that allows engineers to configure its internal logic blocks and routing circuitry after manufacturing to enable custom hardware acceleration and rapid prototyping for specialized computing workloads |
| “FRO”    | full retimed optics, a type of optical transceiver module equipped with digital signal processors (DSPs) on both the transmit and receive paths that can retime, reshape, and reamplify data signals to ensure maximum signal integrity in high-speed network communications  |
| “FTTX”   | fiber to the X, a generic term for various optical fiber network architectures (such as FTTH, FTTB or FTTN) that deliver broadband connectivity from the network backbone to a point close to or at the end user’s premises                                                   |
| “IP67”   | ingress protection 67, a rating under the IEC 60529 standard indicating total protection against dust ingress (6) and protection against temporary immersion in water up to 1 meter depth for 30 minutes (7)                                                                  |
| “IP68”   | ingress protection 68, a rating under the IEC 60529 standard indicating total protection against dust ingress (6) and protection against continuous immersion in water beyond 1 meter depth under conditions specified by the manufacturer (8)                                |
| “IP6K9K” | ingress protection 6K9K, an automotive-specific protection rating under ISO 20653 indicating complete dust-tightness (6K) and resistance to high-pressure, high-temperature steam-jet cleaning (9K)                                                                           |
| “LIN”    | local interconnect network, a serial communication protocol used in automotive and industrial applications for low-cost, low-speed networking between sensors, actuators and electronic control units                                                                         |
| “LPO”    | linear-drive pluggable optics, an optical module technology that eliminates the digital signal processor (DSP) by using linear analog signal transmission, significantly reducing power consumption and latency in data center interconnects                                  |
| “LRO”    | linear receive optics, an optical module technology that applies linear-drive analog processing on the receive side of the optical link, simplifying the signal path and reducing power consumption compared to conventional DSP-based modules                                |
| “MCU”    | microcontroller unit, a compact integrated circuit containing a processor core, memory and programmable input/output peripherals, designed to govern specific operations in embedded systems                                                                                  |

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| “MEMS”                                         | micro-electro-mechanical systems, a technology that integrates miniaturized mechanical and electromechanical elements (such as sensors, actuators and structures) on a silicon substrate using microfabrication techniques                           |
| “MES”                                          | manufacturing execution system, a software system used in manufacturing operations to monitor, track, document and control the production process in real-time from raw materials to finished goods                                                  |
| “MOX”                                          | metal oxide (semiconductor), a gas sensing technology that detects target gases by measuring changes in the electrical resistance of a metal oxide thin film when exposed to the gas, widely used in air quality and safety monitoring applications  |
| “NEV”                                          | new energy vehicle, a vehicle powered wholly or partly by new energy sources such as battery electric power, hydrogen fuel cells or plug-in hybrid systems, as distinguished from conventional internal combustion engine vehicles                   |
| “new energy and intelligent connected vehicle” | a new generation of automobiles that integrates on-board sensors, controllers, actuators, and communication network technologies to achieve intelligent information exchange between the vehicle and people, other vehicles, roads, and the cloud    |
| “NPO”                                          | near-packaged optics, an optical module architecture that places optical engines in close proximity to the switch ASIC on the circuit board, reducing signal path length, power consumption and latency compared to traditional pluggable modules    |
| “NTC”                                          | negative temperature coefficient (thermistor), a type of thermally sensitive resistor whose resistance decreases as temperature increases, widely used in temperature sensing, monitoring and circuit protection applications                        |
| “OEM”                                          | original equipment manufacturer, a company that manufactures products or components that are purchased by another company and sold under that purchasing company’s brand name                                                                        |
| “optical engine”                               | a highly integrated optoelectronic module that converts electrical signals into optical signals (and vice versa) at the chip level to enable ultra-high bandwidth, low-latency, and power-efficient data transmission in advanced networking systems |
| “OSFP”                                         | octal small form-factor pluggable, a high-density, next-generation optical transceiver form factor designed to support data rates of 400G, 800G, 1.6T and beyond, featuring eight electrical lanes and efficient thermal management                  |

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| “OTA”  | over-the-air, a technology enabling the wireless delivery and installation of software updates, firmware patches and configuration changes to devices remotely, without requiring physical access or cable connections                                                                        |
| “PAM4” | pulse amplitude modulation 4-level, a signal modulation scheme that encodes two bits of data per symbol using four distinct amplitude levels                                                                                                                                                  |
| “PCB”  | printed circuit board, a flat board made of insulating material with conductive copper pathways etched or printed onto it, used to mechanically support and electrically connect electronic components in a circuit                                                                           |
| “PON”  | passive optical network, a fiber-optic telecommunications technology for delivering broadband network access that uses unpowered (passive) optical splitters to distribute a single optical fiber signal to multiple customer endpoints                                                       |
| “PTC”  | positive temperature coefficient (thermistor/heater), a type of ceramic heating element or thermistor whose electrical resistance increases sharply with rising temperature, enabling self-regulating heating in applications such as automotive cabin heaters and battery thermal management |
| “PWM”  | pulse width modulation, a technique for controlling power delivery to electrical devices by varying the duty cycle (on-off ratio) of a pulsed signal, widely used in motor control, LED dimming and power regulation                                                                          |
| “R290” | R290 (propane), a natural hydrocarbon refrigerant with very low global warming potential (GWP of 3), used as an environmentally friendly alternative to synthetic refrigerants in refrigeration and air conditioning systems                                                                  |
| “SLM”  | selective laser melting, an additive manufacturing (3D printing) process that uses a high-power-density laser to fully melt and fuse metallic powder particles layer by layer, building dense three-dimensional metal parts directly from digital models                                      |
| “TGV”  | through glass via, a technology that creates vertical electrical interconnections through glass substrates by forming micro-holes, enabling compact, high-density packaging for advanced semiconductor, display and sensor applications                                                       |
| “TVOC” | total volatile organic compounds, a collective measurement of the total concentration of multiple volatile organic compounds present simultaneously in the air, used as an aggregate indicator of indoor or ambient air quality                                                               |

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| “TWS” | true wireless stereo, a wireless audio technology that enables completely cable-free earbuds or headphones to deliver independent stereo sound to each ear via Bluetooth connectivity, without any wire between the two earpieces                                                            |
| “UAV” | unmanned aerial vehicle, a pilotless aircraft operated by remote control or autonomous flight systems, commonly known as a drone, used for applications including aerial photography, surveying, delivery, agriculture and military reconnaissance                                           |
| “UL”  | Underwriters Laboratories, a global independent safety science organization that tests, certifies and validates products, components and systems for safety, quality and sustainability compliance across multiple industries                                                                |
| “UV”  | ultraviolet (laser), a laser emitting light in the ultraviolet spectrum with wavelengths shorter than visible light (typically 355nm or below), used in high-precision micro-cutting and processing of materials due to its short wavelength and minimal thermal damage to surrounding areas |
| “XPO” | extended-packaged optics, an emerging optical module packaging architecture that extends the concept of co-packaged optics with greater design flexibility in the placement and integration of optical engines relative to the switch ASIC                                                   |